


## APPLICATION DATA SHEET

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<b>Title of Invention</b>	[BUMP PROCESS FOR FLIP CHIP PACKAGE]		
Application Type : regular, utility Attorney Docket Number : 10665-US-PA			
Correspondence address: Customer Number: 31561 			
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as our attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.